

AER8121 UV ERASER CONFIGURED FOR 8" AND 12" WAFER

SN	Feature		CEI Specified	Remarks
1	Module Function		UV Eraser for 12" & 8" standard silicon wafer	
2	Input Media	200mm wafer	Thickness : 225 - 750um Warpage ≤ 1.5 mm in 25 slot cassette	
		300mm wafer	Thickness : 300 - 750um Warpage ≤ 2 mm in 25 slot cassette	
3	FOSB / FOUP / Cassette	300mm FOSB / FOUP	25 slot FOSB	
			25 slot FOUP	
			Metal cassette (customer need provide drawing and sample)	
		200mm Cassette	25 slot H-Type cassette 13 slot H-Type cassette Metal cassette (customer need provide drawing and sample)	
4	FOSB / FOUP / Cassette Mapping		1. Able to detect ABSENCE, PRESENCE, DOUBLE & CROSS SLOT 2. Cassette Mapping function will enable software prompt for action (buzzer) for any possible wafer damage caused by CROSS or warpage, etc.. Machine to log such record.	
5	Aligner	Wafer type	Notch or Flat finding	
6	OCR Reader	Top Side Reading	To Read on 200mm To Read on 300mm	Auto convert Pneumatic OCR Module to read on 200mm and 300mm wafer
7	Robot	5-axis Robot	- Dual Arm Wafer Robot - 5-axis with X-axis - Ceramic end effector	
8	UV Module	capability	One UV module with two UV chamber, max three modules	
			One wafer in UV chamber	
			With UV online monitor and temperture monitor in chamber	
		UV lamp specification	12" x 12" grid lamp Wavelength 254 nm Intensity 60 \pm 10% mW/cm2 at distance of 1" Warm up 15 mins Lifespan: 1500 hrs& its intensity decrease by 50% after 1500 hrs of operation	
9	Machine outlook and facility	Covers	Mild steel with power coating(smooth finish) and transperent covers:	
		Facility requirement	Frequency: 50/60 Hz Voltage: 220V +/- 10% Main machine current: 25 Amps Per UV module current: 15 Amps (Max 3 modules) Air: min 70 PSI via \varnothing 10mm tubing Vaccum: 22 to 25 in-Hg via \varnothing 12mm tubing	
10	Machine Control	Main	CEI MMI, Bar Code Reader	
		Monitor	19" Touch LCD Flat Panel Monitor	
		Tower Light	RED/AMBER/GREEN for indicating machine status/warning	
		Networking	SEC/Gem (Option)	
11	Working Height:		Approximately 900mm from floor to cassette sit plane	
12	Dimensions	with Filter, Monitor and loadports	Approximately for 2 UV modules: 1930mm(L)x2050mm(W)x1960mm(H) Approximately for 3 UV modules: 2655mm(L)x2050mm(W)x1960mm(H)	Refer to "Machine Layout"
13	Environment	Clean Room requirement	Class 100 with ULPA Filter	
		Noise Level	less then 70 - 80 dB	
14	Performance		MCBA < 1000 Cycles MCBF < 3000 Cycles MTTR < 8Hrs Wafer damage 1 ppm Wafer Scratch (non active side) 1 ppm	
15	Machine WPH		11 wafers@ 20 min cure time – 2.27 hour for 25-wafer cassette 15 wafers@ 15 min cure time – 1.67 hour for 25- wafer cassette (Based on 4 UV chambers, 1 wafer/chamber)	
16	Others Requirement		ESD compliance	